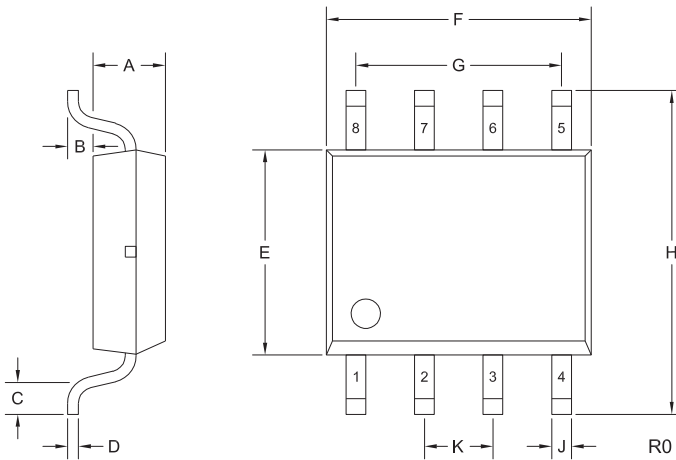


Package Details

SOIC-8 Case



Mechanical Drawing



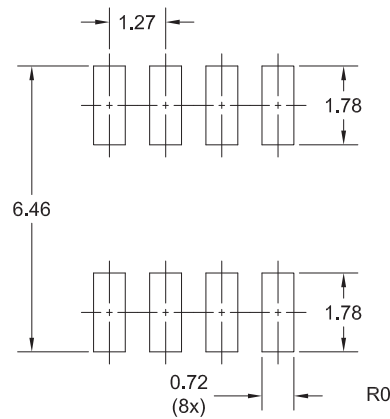
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.049	0.057	1.24	1.44
B	0.000	0.011	0.00	0.27
C	0.018	-	0.46	-
D	0.006	0.011	0.16	0.27
E	0.145	0.154	3.70	3.90
F	0.189	0.198	4.81	5.01
G	0.150		3.81	
H	0.231	0.244	5.88	6.18
J	0.013	0.021	0.35	0.52
K	0.050		1.27	

SOIC-8 (REV: R0)

Lead Code:
Reference individual device datasheet.

Part Marking:
4-5 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



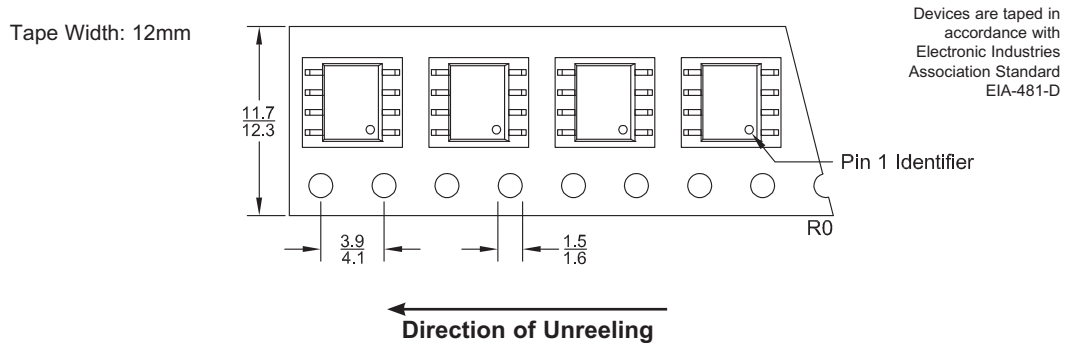
R0 (27-March 2013)

Package Details

SOIC-8 Case



Tape Dimensions and Orientation (Dimensions in mm)



Packaging Base

13" Reel = 2,500 pcs.

Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13"	5	12,500	15x4x15	38x10x38	8	4
	14	35,000	15x15x9	38x38x23	19	9
	26	65,000	15x15x18	38x38x46	34	16

Ordering Information

- For devices taped and reeled on 13" reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R0 (27-March 2013)

Material Composition Specification

SOIC-8 Case



Device average mass 74.6 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.43%	0.32	Si	7440-21-3	0.43%	0.32	4,290
bond wire	copper	0.03%	0.02	Cu	7440-50-8	0.03%	0.02	268
leadframe	Cu alloy w/ silver plating	38.87%	29	Cu	7440-50-8	37.47%	27.95	374,665
				Fe	7439-89-6	0.912%	0.68	9,115
				P	7723-14-0	0.027%	0.02	268
				Zn	7440-66-6	0.04%	0.03	402
				Ag	7440-22-4	0.429%	0.32	4,290
die attach	silver epoxy	0.094%	0.07	Ag	7440-22-4	0.075%	0.056	751
				epoxy resin	Proprietary	0.019%	0.014	188
encapsulation*	EMC GREEN	60.56%	45.2	silica (fused)	60676-86-0	42.9%	32	428,954
				epoxy resin	29690-82-2	5.63%	4.2	56,300
				phenol resin	9003-35-4	5.63%	4.2	56,300
				carbon black	1333-86-4	0.31%	0.23	3,083
				metal hydroxide	1309-42-8	6.1%	4.55	60,992
plating	matte tin	0.013%	0.01	Sn	7440-31-5	0.013%	0.01	134

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (1-May 2012)